


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 24 October 2022 [Approved on 29 January 2026, 13:40 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.78%	Silicon	7440-21-3	100%
Die attach	Lead and Lead alloys	0.67%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	52.89%	Carbon black	1333-86-4	1%
			Magnesium hydroxide (Mg(OH) ₂)	1309-42-8	3%
			Phenol, polymer with formaldehyde	9003-35-4	8%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz (SiO₂) Exempt from other regulatory requirements	14808-60-7	78%
Leadfinish	Tin plating	0.01%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	45.65%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-214AA/SMB_(JS)_H-free	Diode SMD	0.0930004	g
